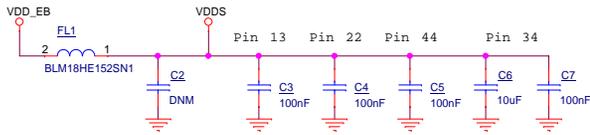
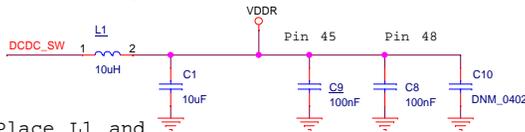


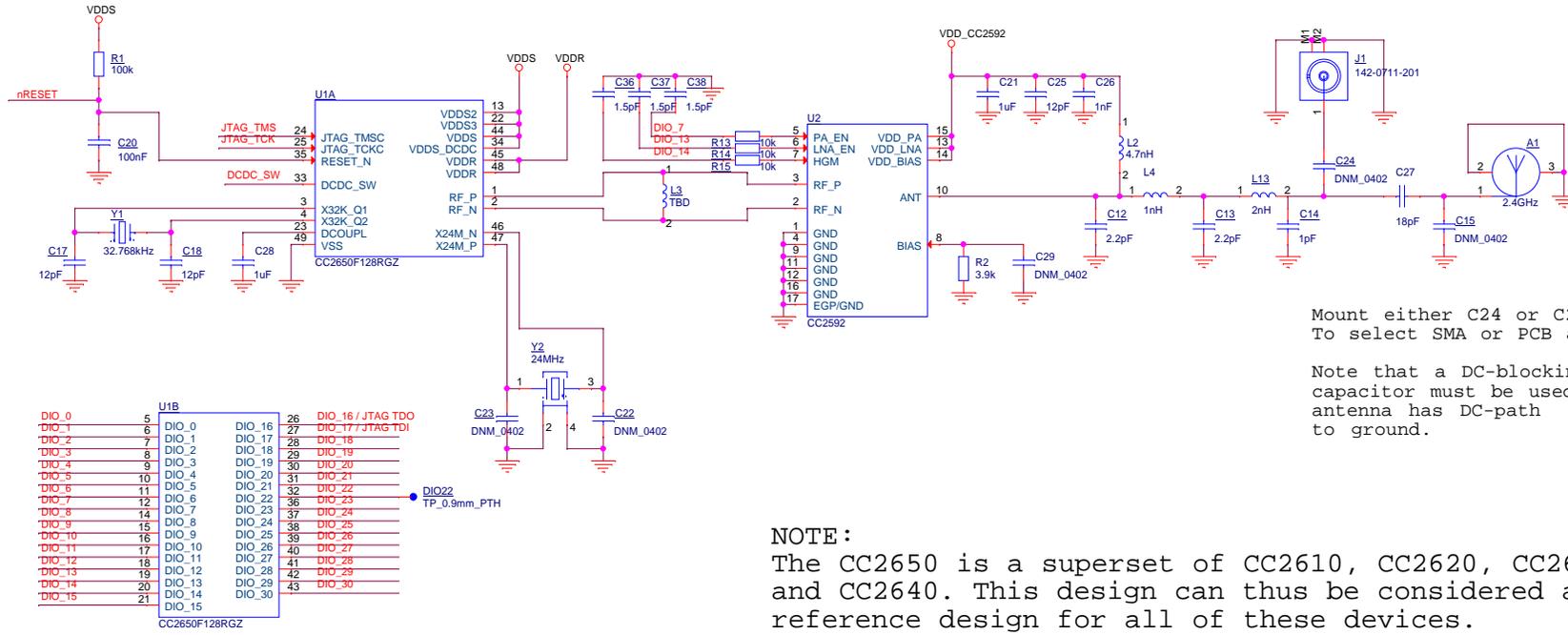
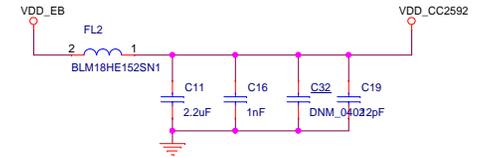
VDDS Decoupling Capacitors for CC2650



VDDR Decoupling Capacitors for CC2650



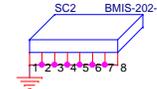
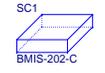
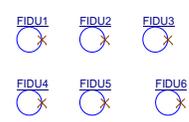
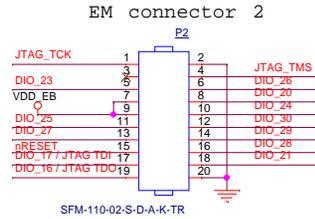
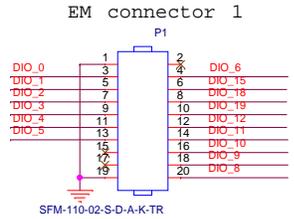
Place L1 and C8 close to pin 33



Mount either C24 or C27 To select SMA or PCB ant.
Note that a DC-blocking capacitor must be used if antenna has DC-path to ground.

NOTE:
The CC2650 is a superset of CC2610, CC2620, CC2630 and CC2640. This design can thus be considered a reference design for all of these devices.

Likewise, the CC2650EM board can be used to evaluate the performance for all the above mentioned devices.



Title: TIDC-CC2650-CC2592-EMK		
Drawn: SVS		
Checked:		
Size: A3	Rev: Rev 1.1.0	Sheet: 1 of 1
Date: Wednesday, November 18, 2015		

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